

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0	0.66	0.07
	Doped silicon	Silicon (Si)	7440-21-3	0.17	99.34	9.93
		<b>Subtotal</b>		<b>0.17</b>	<b>100</b>	<b>10</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.2
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	66.89	99.87	3984.81
		<b>Subtotal</b>		<b>66.98</b>	<b>100</b>	<b>3990</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.09	6.5	124.34
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.14	16.0	306.08
	Filler	Silica fused	60676-86-0	22.8	71.0	1358.23
	Flame retardant	Metal hydroxide		2.09	6.5	124.34
		<b>Subtotal</b>		<b>32.12</b>	<b>100</b>	<b>1912.99</b>
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.37	100.0	22
		<b>Subtotal</b>		<b>0.37</b>	<b>100</b>	<b>22</b>
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01	5.0	0.4
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.2
	Lead alloy	Lead (Pb)	7439-92-1	0.12	92.5	7.4
		<b>Subtotal</b>		<b>0.13</b>	<b>100</b>	<b>8</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.24	100.0	14
		<b>Subtotal</b>		<b>0.24</b>	<b>100</b>	<b>14</b>
		<b>Total</b>		<b>100.01</b>	<b>100</b>	<b>5956.99</b>

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